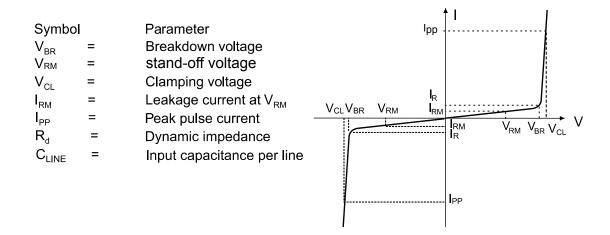


1 Characteristics

Table 1. Absolute ratings (T_{amb} = 25 °C)

Symbol		Value	Unit			
		Contact discharge	30			
		Air discharge	30			
		ISO 10605 - C = 330 pF, R = 330 Ω:	ESDCAN24-2BLY			
V_{PP}	Peak pulse voltage	Contact discharge	ESDCAN01-2BLY	30	kV	
		Air discharge	ESDCAN04-2BLY	30		
		ISO 10605 - C = 330 pF, R = 330 Ω : Contact discharge ESDCAN06-2BLY				
				22		
		Air discharge		22		
	D 1 1 10/0		ESDCAN01-2BLY	5.5		
I _{PP}	Peak pulse current (8/2	20 μs)	ESDCAN04-2BLY	3.7	Α	
		3				
Tj	Operating junction tem	perature range		-40 to +150	°C	
T _{stg}	Storage temperature ra	inge		-55 to +150	°C	

Figure 1. Electrical characteristics (definitions)



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Table 2. Electrical characteristics (values, T_{amb} = 25 °C)

	I _{RM} max. at V _{RM}		V _{BR} at I _R		R	V _{CL} Pulse ISO7637-3		V _{CL} at I _{PP} (8/20 μs)		С		ΔC ⁽¹⁾	αT ⁽²⁾
Order code			Min.	Max.		3a at -150 V min.	3b at +150 V max.	Max.		Тур.	Max.	Тур.	Тур.
	μΑ	٧	,	V	mA	,	V	V	Α	þ	F	рF	10 ⁻⁴ /°C
ESDCAN24-2BLY	0.1	24	27	32	1	-40	40	43	5	-	30	0.1	9
ESDCAN01-2BLY	0.1	24	25	30	1	-35	35	40	5	-	30	0.1	9
ESDCAN04-2BLY	0.05	25.5	27.5	30.7	1	-35	35	43	3	17	19	0.1	9
ESDCAN06-2BLY	0.1	35	38	42.2	1	-44	44	59	3	13	15	0.1	9

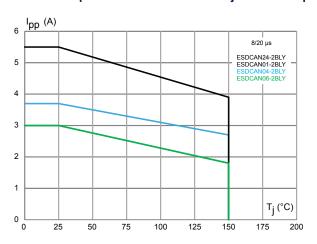
^{1.} ΔC : capacitance variation between IO1 and IO2 versus GND

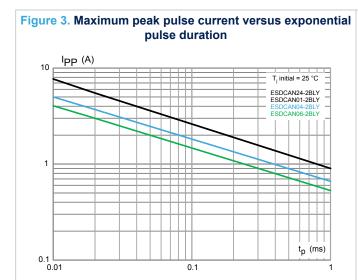
^{2.} to calculate V_{BR} versus T_j : V_{BR} at $T_j = V_{BR}$ at 25 °C x (1 + αT x (T_j - 25))

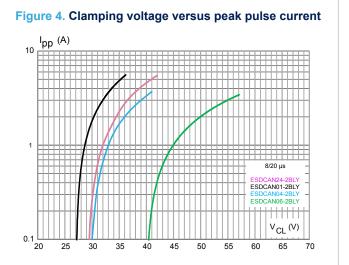


1.1 Characteristics (curves)

Figure 2. Maximum peak current versus initial junction temperature







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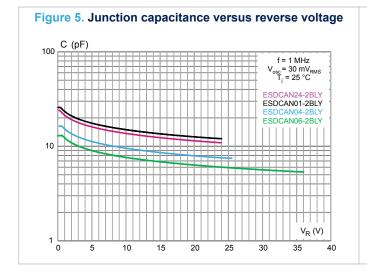


Figure 6. Leakage current versus junction temperature

Figure 7. Response to ISO 10605 -C = 150 pF, R = 330 Ω
(-8 kV contact)

ESDCAN24-2BLY

ESDCAN01-2BLY

ESDCAN06-2BLY

50 V/div
20 ns/div

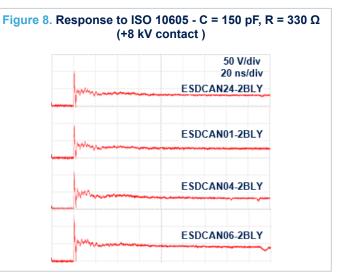
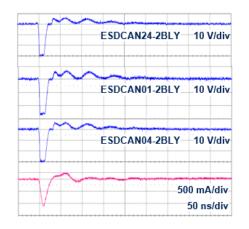
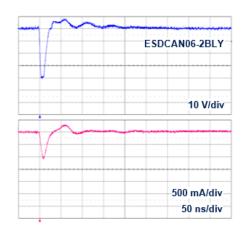
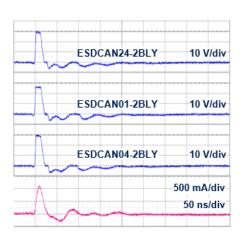


Figure 9. Response to ISO 7637-3 Pulse 3a: -150 V





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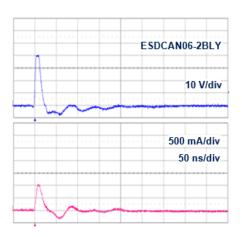
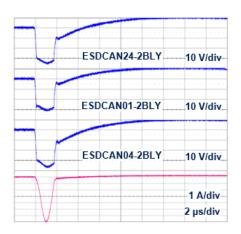


Figure 11. Response to ISO 7637-3 pulse 2a: -85 V

Figure 10. Response to ISO 7637-3 Pulse 3b: +150 V



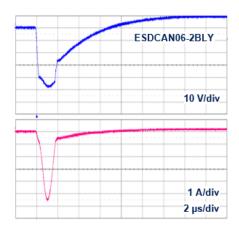
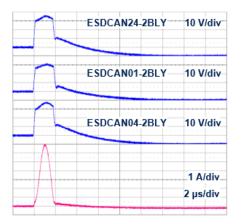
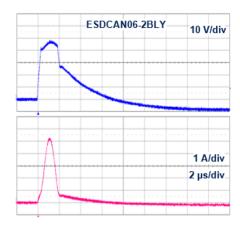


Figure 12. Response to ISO 7637-3 pulse 2a: +85 V

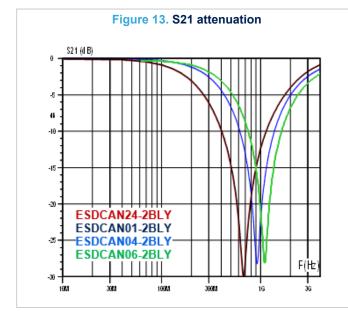


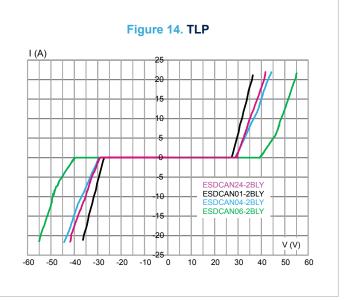


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Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

2.1 SOT23-3L package information

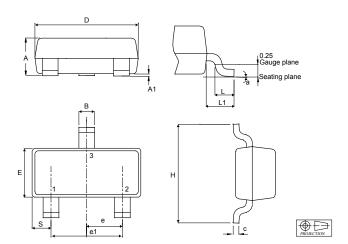


Figure 15. SOT23-3L package outline

Table 3. SOT23-3L package mechanical data

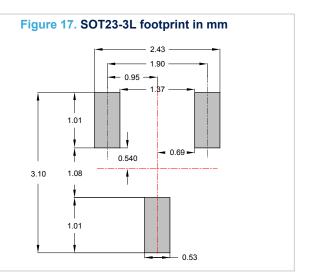
	Dimensions								
Ref.		Millimeters		Inches ⁽¹⁾					
	Min.	Тур.	Max.	Min.	Тур.	Max.			
Α	0.89		1.25	0.0350		0.050			
A1	0.00		0.15	0.0000		0.006			
В	0.30		0.51	0.011		0.021			
С	0.085		0.20	0.003		0.008			
D	2.75		3.04	0.108		0.120			
Е	1.20		1.75	0.047		0.069			
е	0.85	0.95	1.05	0.033	0.037	0.042			
e1	1.70	1.90	2.10	0.066	0.075	0.083			
Н	2.10		3.00	0.082		0.119			
L	0.25		0.61	0.009		0.025			
L1		0.55			0.022				
S	0.35		0.65	0.013		0.026			
а	0°		8°	0°		8°			

^{1.} Dimension in inches are given for reference only.

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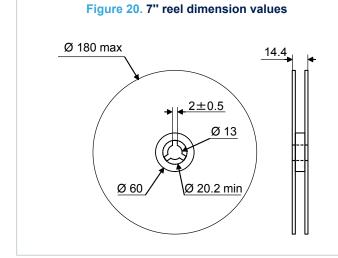
XXXX: Marking

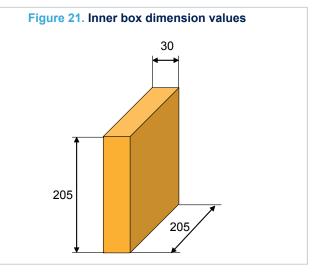


Pin 1 located according to EIA-481

Note: Pocket dimensions are not on scale Pocket shape may vary depending on package



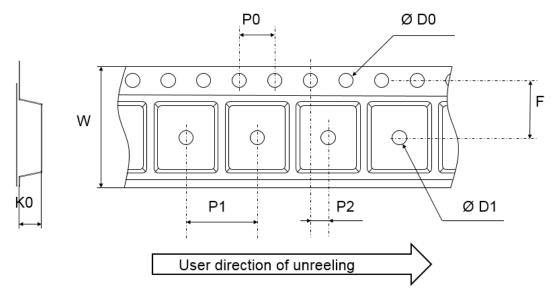




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Figure 22. Tape outline



Note: Pocket dimensions are not on scale Pocket shape may vary depending on package

Table 4. Tape dimension values

	Dimensions							
Ref.	Millimeters							
	Min.	Тур.	Max.					
D0	1.45	1.5	1.6					
D1	1							
F	3.45	3.5	3.55					
K0	1.3	1.4	1.5					
P0	3.9	4.0	4.1					
P1	3.9	4.0	4.1					
P2	1.95	2.0	2.05					
W	7.9	8	8.3					

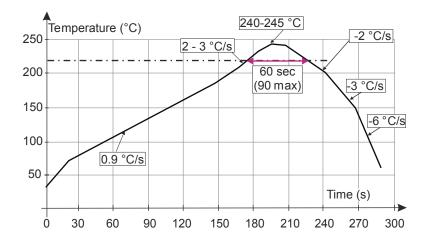
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3 Reflow profile

Figure 23. ST ECOPACK® recommended soldering reflow profile for PCB mounting



Note: Minimize air convection currents in the reflow oven to avoid component movement. Maximum soldering profile corresponds to the latest IPC/JEDEC J-STD-020.

Downloaded from Arrow.com.



4 Ordering information

Figure 24. Ordering information scheme

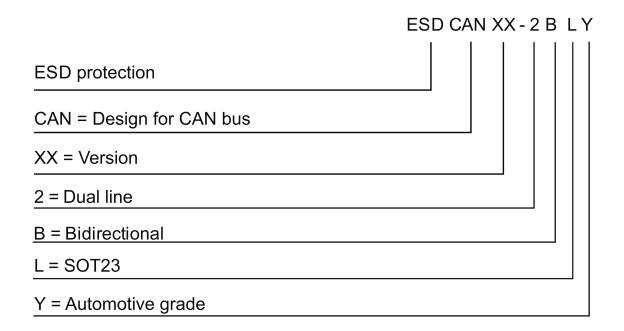


Table 5. Ordering information

Order code	Marking ⁽¹⁾	Package	Weight	Base qty.	Delivery mode	
ESDCAN24-2BLY	EL24		9.8 mg	3000		
ESDCAN01-2BLY	EN24	SOT23-3L			Tape and reel	
ESDCAN04-2BLY	EC24	50123-3L				
ESDCAN06-2BLY	EC35					

^{1.} The marking can be rotated by multiples of 90° to differentiate assembly location

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Revision history

Table 6. Document revision history

Date	Revision	Changes		
13-Jul-2015	1	First issue.		
		Added RPN ESDCAN04-2BLY and ESDCAN06-2BLY.		
04-Oct-2018	2	Updated cover page, Section 1 Characteristics and Section 1.1 Characteristics (curves).		
		Added Packing information.		
05-Apr-2019	3	Added typical pitch in Table 3 and updated Figure 17.		

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